lenb

3: Cathode 2

Package

SMini4-F2

Pin Name

1: Anode 1

Code

MA4ZD030G

Silicon epitaxial planar type

For high speed switching For small type power supply For DC/DC converter

Features

- Two isolated elements are contained in one package, allowing high-density mounting
- $I_F = 100 \text{ mA}$ rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time (t_{rr})



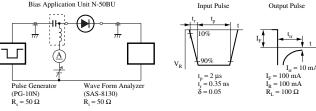
Electrical Characteristics

Parameter	Sympol	Conditions	Min	Тур	Max	Unit
Reverse current	I _R	$V_R = 40 V$			5	μΑ
Forward yoltage	V _F	$I_F = 100 \text{ mA}$		0.54	0.60	V
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		12	18	pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$			1.2	ns
N NO KUN		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

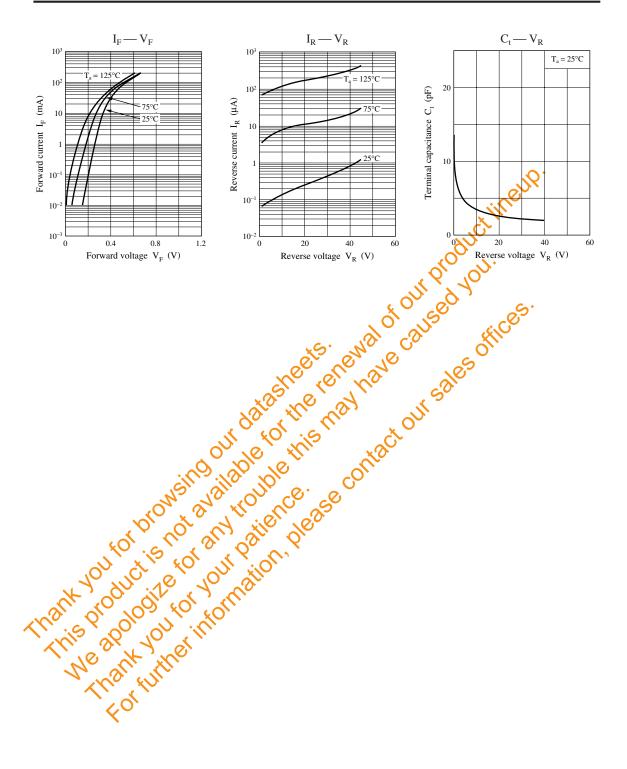
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 250 MHz.
- Bias Application Unit N-50BU 4.*: trr measurement circuit



MA4ZD030G

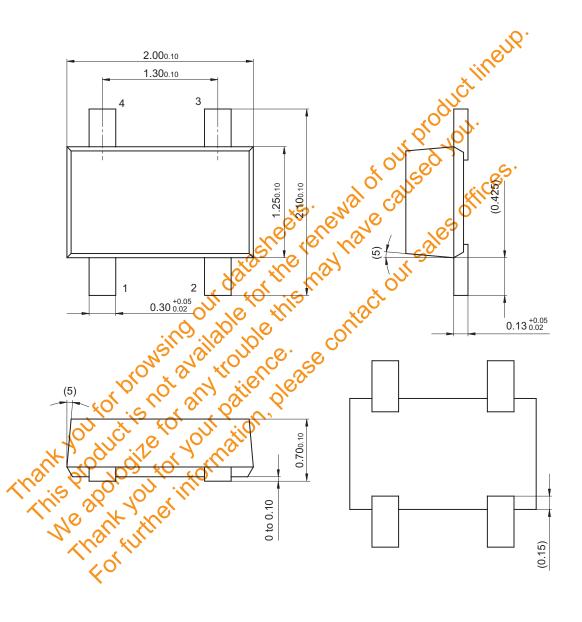
Panasonic



Panasonic

SMini4-F2

Unit: mm



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